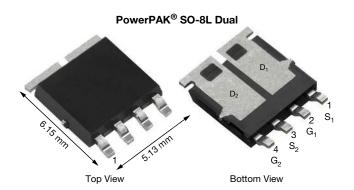


Vishay Siliconix

Automotive Dual N-Channel 40 V (D-S) 175 °C MOSFET



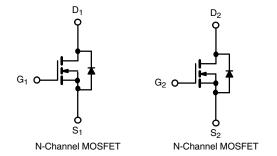
PRODUCT SUMMARY				
V _{DS} (V)	40			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.008			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.010			
I _D (A) per leg	30			
Configuration	Dual			

FEATURES

- TrenchFET® Gen IV Power MOSFET
- AEC-Q101 qualified
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJB46ELP (for detailed order number please see www.vishay.com/doc?79771)

ABSOLUTE MAXIMUM RATINGS	G (T _C = 25 °C, unles	ss otherwise noted	1)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage		V_{DS}	40	V	
Gate-source voltage		V_{GS}	V _{GS} ± 20		
Continuous drain current	T _C = 25 °C ^a	1	30		
Continuous drain current	T _C = 125 °C	I _D	27		
Continuous source current (diode conduction)	а	I _S	30	Α	
Pulsed drain current ^b		I _{DM}	120		
Single pulse avalanche current L = 0.1 mH		I _{AS}	20.5		
Single pulse avalanche energy	L=0.1 IIII	E _{AS}	21	mJ	
Maximum power dissipation	T _C = 25 °C	25 °C 34		W	
Maximum power dissipation	T _C = 125 °C	r _D	11	VV	
$T_{C} = 125 ^{\circ}{\text{C}}$ Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature	re) d		260		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount ^c	R_{thJA}	85	°C/W
Junction-to-case (drain)		R_{thJC}	4.3	C/VV

Notes

- a. Package limited
- b. Pulse test; pulse width $\leq 300 \,\mu\text{s}$, duty cycle $\leq 2 \,\%$
- c. When mounted on 1" square PCB (FR4 material)
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leaded package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	40	-	-	V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	1.2	1.7	2.2	V
Gate-source leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA
		V _{GS} = 0 V	V _{DS} = 40 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 40 V, T _J = 125 °C	-	-	50	μΑ
		V _{GS} = 0 V	V _{DS} = 40 V, T _J = 175 °C	-	-	250	
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 \text{ V}$	25	-	-	Α
		V _{GS} = 10 V	I _D = 8 A	-	0.0064	0.0080	
Dynin anywas an atata yasiatanaa 3		V _{GS} = 10 V	I _D = 8 A, T _J = 125 °C	-	-	0.0131	
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 8 A, T _J = 175 °C	-	-	0.0157	Ω
		V _{GS} = 4.5 V	I _D = 5 A	-	0.0080	0.0100	
Forward transconductance b	9fs	V _{DS}	= 15 V, I _D = 8 A	-	46	-	S
Dynamic ^b							
Input capacitance	C _{iss}			-	1499	2100	
Output capacitance	Coss	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	426	600	рF
Reverse transfer capacitance	C _{rss}			-	34	48	
Total gate charge ^c	Qg			-	26	40	
Gate-source charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 20 \text{ V}, I_D = 3 \text{ A}$	-	4.3	-	nC
Gate-drain charge ^c	Q _{gd}			-	4.3	-	
Gate resistance	R_g		f = 1 MHz	1.26	2.54	3.8	Ω
Turn-on delay time ^c	t _{d(on)}			-	10	20	
Rise time ^c	t _r	$V_{DD} =$	20 V, R_L = 6.67 Ω	-	5	10	ns
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 3 A, Y$	V_{GEN} = 10 V, R_g = 1 Ω	-	25	40	
Fall time ^c	t _f			-	6	12	
Source-Drain Diode Ratings and Chara	cteristics ^b						
Pulsed current ^a	I _{SM}			-	-	120	Α
Forward voltage	V _{SD}	l _F =	= 8 A, V _{GS} = 0 V	-	0.79	1.2	V
Body diode reverse recovery time	t _{rr}			-	26	55	ns
Body diode reverse recovery charge	Q _{rr}		1 0 4 37/41 400 4/		15	33	nC
Reverse recovery fall time	ta	I _F = 6 A, di/dt = 100 A/μs		-	13	-	
Reverse recovery rise time	t _b			-	13	-	ns
Body diode peak reverse recovery	I _{RM(REC)}			_	-0.97	_	Α

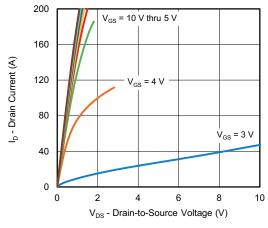
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

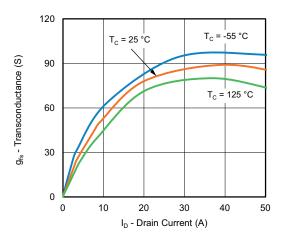
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



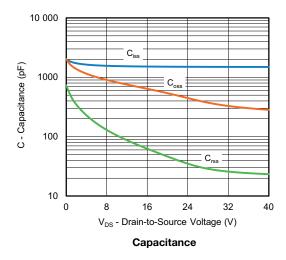
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

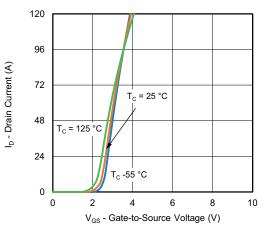


Output Characteristics

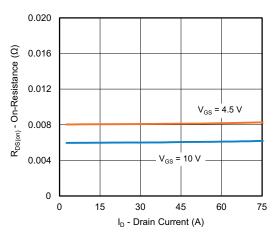


Transconductance

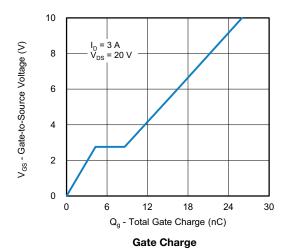




Transfer Characteristics

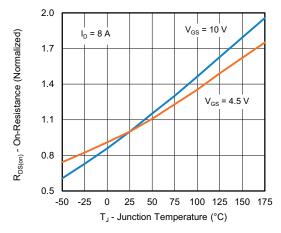


On-Resistance vs. Drain Current

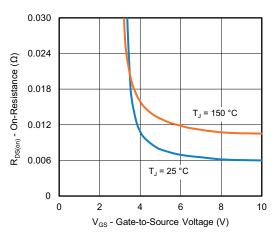




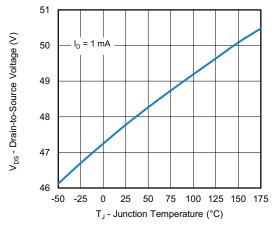
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature

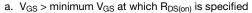


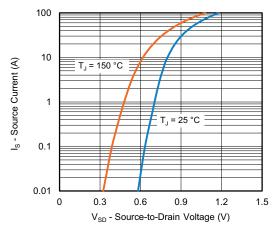
On-Resistance vs. Gate-to-Source Voltage



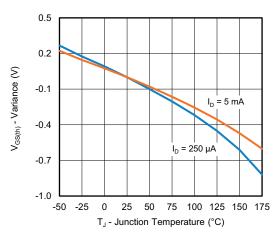
Drain Source Breakdown vs. Junction Temperature

Note

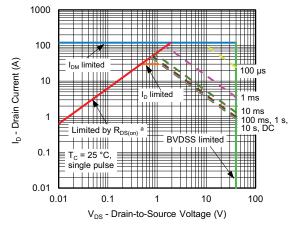




Source Drain Diode Forward Voltage



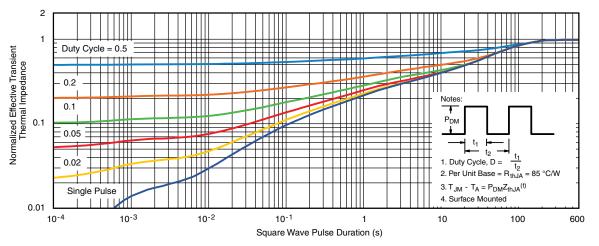
Threshold Voltage



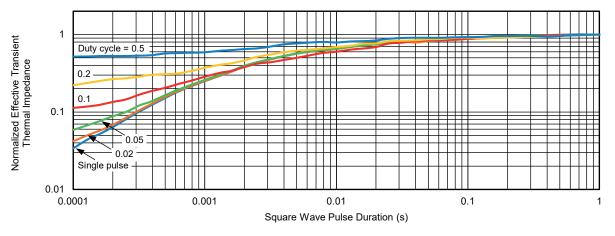
Safe Operating Area



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

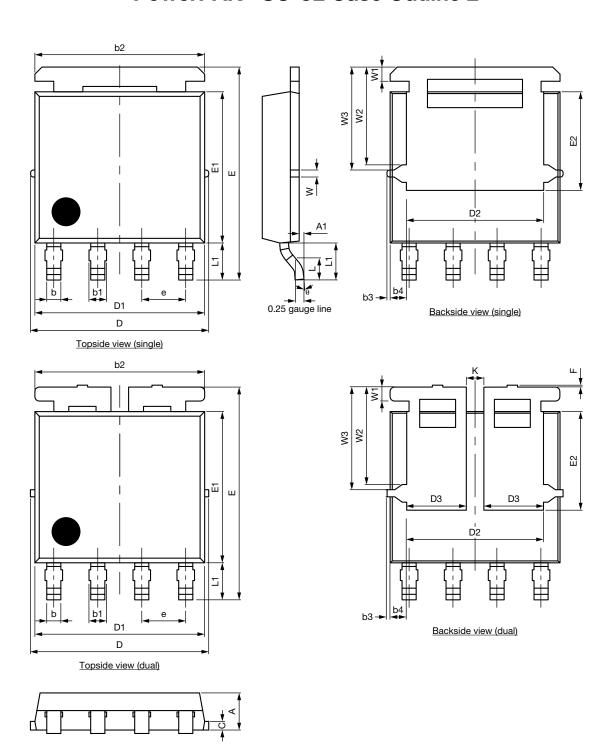
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?77402.



PowerPAK® SO-8L Case Outline 2



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DIM		MILLIMETERS		INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094	_		0.004	•	
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC	•		0.050 BSC		
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51	•	0.020			
W		0.23			0.009		
W1		0.41			0.016		
W2		2.82			0.111		
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

ECN: C21-1498-Rev. C, 01-Nov-2021

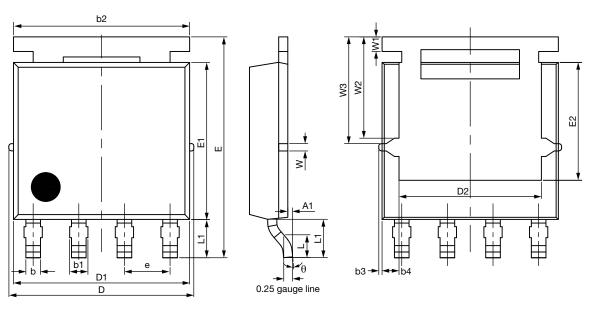
DWG: 6044

Note

• Millimeters will govern

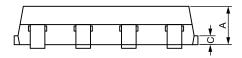


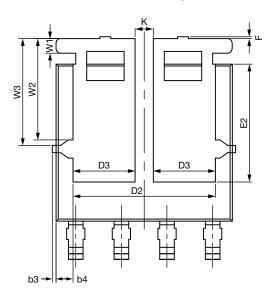
PowerPAK® SO-8L Case Outline 1



Topside view

Backside view (single)





Backside view (dual)



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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.133	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51		0.020			
W		0.23			0.009		
W1		0.41			0.016		
W2		2.82			0.111		
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

ECN: S19-0643-Rev. E, 05-Aug-2019

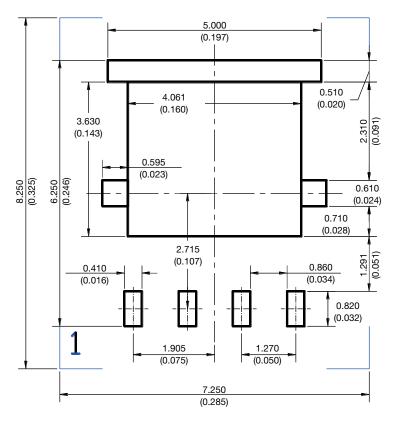
DWG: 5976

Note

Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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